

# LNJ937W8CRA

## High Bright Surface Mounting Chip LED

ESS II Type

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Power dissipation	$P_D$	40	mW
Forward current	$I_F$	10	mA
Pulse forward current *	$I_{FP}$	55	mA
Reverse voltage	$V_R$	5	V
Operating ambient temperature	$T_{opr}$	-30 to +85	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-40 to +100	$^\circ\text{C}$

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

### ■ Lighting Color

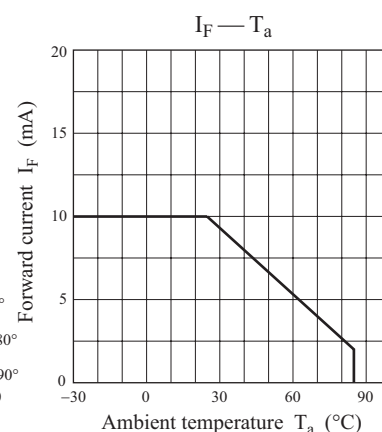
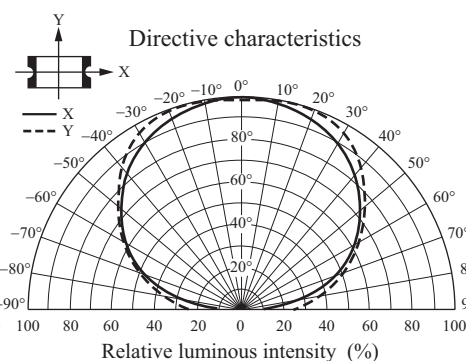
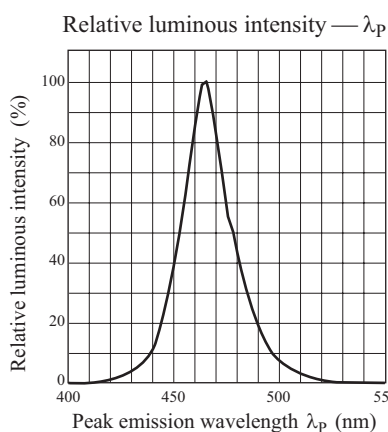
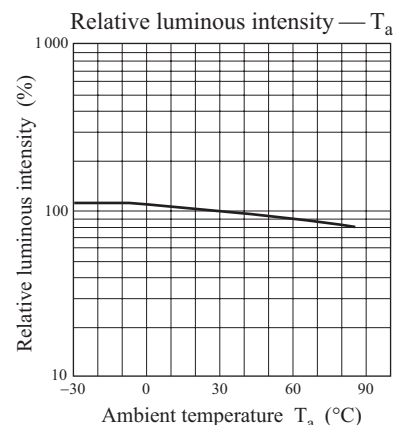
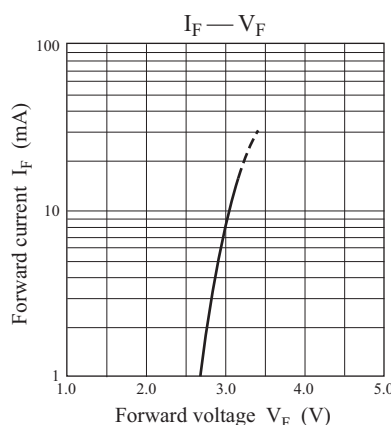
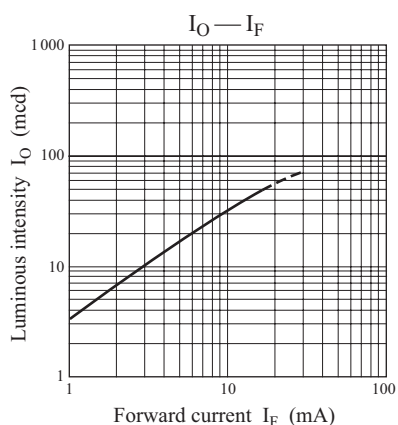
- Blue

### ■ Electro-Optical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

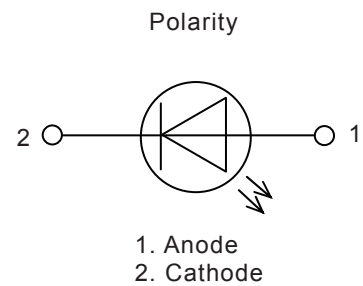
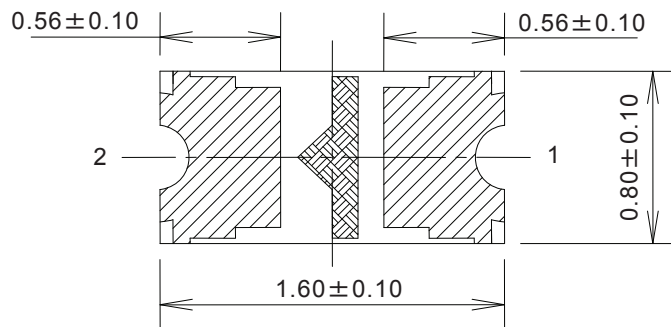
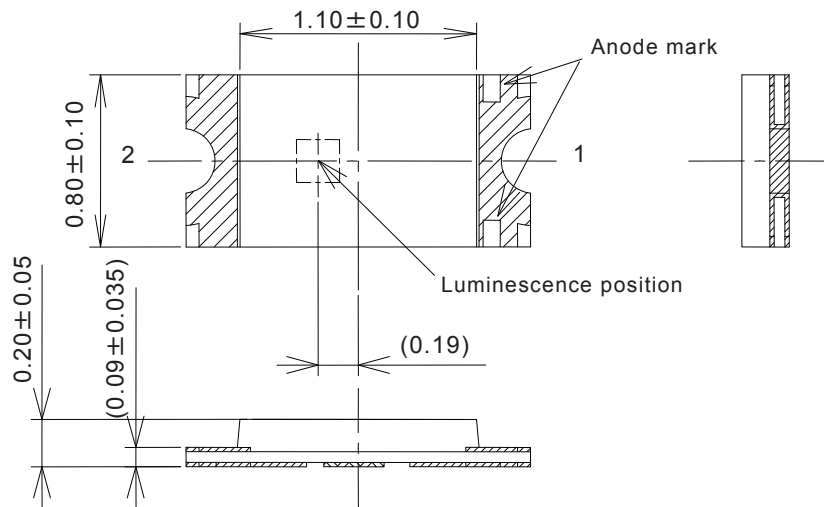
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity *1	$I_O$	$I_F = 5 \text{ mA}$	10.0	17.0	30.0	mcd
Reverse current	$I_R$	$V_R = 5 \text{ V}$			100	$\mu\text{A}$
Forward voltage	$V_F$	$I_F = 5 \text{ mA}$		2.9	3.2	V
Peak emission wavelength	$\lambda_p$	$I_F = 5 \text{ mA}$		465		nm
Dominant emission wavelength *2	$\lambda_d$	$I_F = 5 \text{ mA}$	462	472	478	nm
Spectral half band width	$\Delta\lambda$	$I_F = 5 \text{ mA}$		20		nm

Note) \*1: Measurement tolerance:  $\pm 20\%$

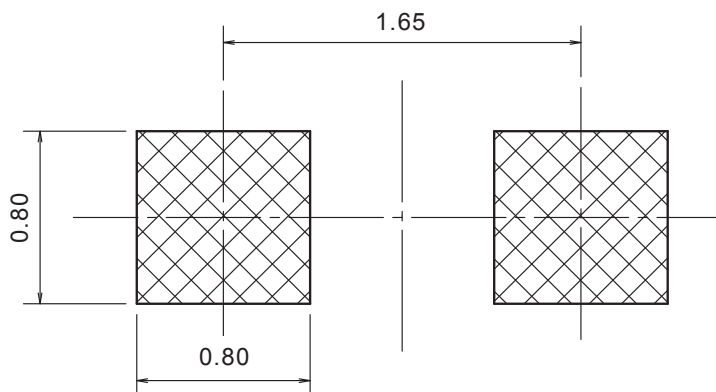
\*2: Measurement tolerance:  $\pm 2 \text{ nm}$



■ Package (Unit: mm)



**Recommended Land Layout**



(Note1) Electrode projection is not included in the package dimensions.

(Note2) About solder thickness, please examine the products yourself completely.

(Recommended thickness :  $t=0.10$  mm~ $0.15$  mm)

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